

WEBENCH® Allegro Connector

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ABSTRACT

The purpose of this document is to provide information on the features available in this release of WEBENCH Allegro Connector. It also contains details about the known issues and limitations of this software.

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1 Feature Available

- Import WEBENCH Designs
- Integration with latest release of Allegro 16.6
- GUI to create and edit WBSE simulation setting files
- One-click solution to provide optimised settings for PSpice models with Abrupt transitions
- WBSE version used is 4.2.3
- Supports installation in path with spaces. For example in Program Files
- Supports the Allegro Projects paths with spaces
- Start Menu entries are unified under Texas Instruments directory
- Supports importing simulation settings from existing Pspice SIM file
- Saving WBSE simulation settings with Allegro Project
- Updated documentation. Help documentation is available in CHM and PDF formats.
- New simulation status UI

2 Fixed/New in this Release

2.1 c1.3.2-s.4.2.3

- Added Import WEBENCH xml feature
- Added more WEBENCH Designer links
- Updated the User Guide and 'About' info
- Rearranged WEBENCH menu item for 16.6

2.2 RC3

- Fixed issue with path
- Old Simulation profile is not working
- Make flow consistent with DAT file format
- Window do not resize properly while changing the analysis
- Make Capture free when WBSE simulation is running
- Bind Enter and Esc key to the UI
- Custom/Additional options are not getting cleared when a new simulation profile is created
- Simulation profile is not getting deleted
- Simulation is not running, and no command window opens up
- UI does not come up when multiple projects are open and at least one of them does not have any simulation profile.

2.3 RC2

View waveform function is fixed

2.4 RC1

- Capability for generating WEBENCH netlist, usable by CIR2TIS Perl script
- UI controls provided for OPTSTEP, TSTEP and LTERELRATIO

2.5 RC

- GUI generated netlists are compatible to cir2tis generated netlists
- Toolbar icons have been updated to graphical icons
- Issue with toolbar in SPB 16.6 have been fixed (Cadence).

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3 Beta 4

- PSpice Markers are supported. Currently markers can be placed only on the top level designs.
- WBSE version upgraded to 4.2.1
- Direct DAT file generation is supported in WBSE, which reduces simulation viewing time significantly. Currently it is supported for Allegro SPB 16.3 and SPB 16.5.

4 Beta 3

- Enable library is integrated with WEBENCH Allegro Connector installer
- Enable library documentation is integrated
- WBSE User Manual is integrated in WEBENCH Allegro Installer

5 Beta 2.3

- Fixed issue with improper lib file getting added in project reload. Extension was getting removed from filename.
- Enhanced UI with option to select N number of level to select nodes for plotting
- A GUI button is added to reset the simulation settings to default settings
- Toolbar for Allegro 16.6 is removed due to Allegro crash issue. Will be enable after next hotfix release from Cadence.
- Active simulation profile is loaded with the project. User can directly run the simulation if a profile is already saved.
- Fixed issue with LIB files (with name as -1) getting added when user clicks cancel button.
- Fixed the bug regarding improper netlisting when multiple projects are open.

6 Known Issues

- View Simulation Results do not work if any instance of AMS simulator is already opened
- WEBENCH menu items may appear out of sequence while using Allegro 16.5

7 Future Enhancements

- Using already opened instance of AMS simulator to view simulation results
- TI logo for TI ICs
- Correct pin name locations for ICs
- Num CPU option in GUI
- Activate the connector from within Allegro
- Check for Updates for the connector
- Support for isspice parts
- Support WEBNCH import for Filter/Amplifier designs (AC analysis)

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